

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	10697	buffer with pads	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2005/11/14 10:04
L2	1946	buffer with pads with (IC or die or chip or component)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2005/11/14 10:04
L3	923	buffer with pads with (IC or die or chip or component) with output	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2005/11/14 10:04
L4	625	buffer with pads with (IC or die or chip or component) with output with input	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2005/11/14 10:04
L5	173	4 and wafer	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2005/11/14 10:23
L6	7	"361"/\$.ccls. and 5	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2005/11/14 10:23
L7	75	"257"/\$.ccls. and 5	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2005/11/14 10:24
L8	26	"324"/\$.ccls. and 5	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2005/11/14 10:24